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U. S. PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	ALSO DATE IF APPROPRIATE
DM 581135	9/22/98	Kawakita et al.	438	613	11/25/97
DM 542243	6/6/95	Takiar et al.	174	52.4	5/22/92
DM 599416	11/30/99	Akram et al.	438	108	3/10/97
DM 595272	9/14/99	Ball	257	777	1/17/97
DM 560826	2/4/97	Degani et al.	257	723	2/24/95

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation YES NO

OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)

DM	Article, published as part of the 2000 Electronic Components and Tech. Conf. of 05/21/00 - 05/24/00, by Jean Dufresne, "Hybrid Assembly Technology for Flip-Chip-on-Chip (FCOC) Using PBGA Laminate Assembly," Ref. # 0-7803-5908-9/00, IEEE.

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